

**In the Claims:**

Please cancel claims 1-9 and 18-20. The claims are as follows.

1-9. (Canceled)

10. (Original) A method for dissipating heat from an electronic package having one or more components comprising:

    providing a substrate having a first coefficient of thermal expansion;

    attaching a lid to said substrate, said lid including a vapor chamber, the lid having a second coefficient of thermal expansion;

    matching said first coefficient of thermal expansion matched to said second coefficient of expansion;

    providing a thermal transfer medium in contact with a back surface of each component and an outer surface of a lower wall of said lid; and

    electrically connecting each component to a top surface of said substrate.

11. (Original) The method of claim 10, wherein said lower wall of said lid has a third coefficient of thermal expansion and said components have a fourth coefficient of expansion and further including matching said third coefficient of expansion to said fourth coefficient of expansion.

12. (Original) The method of claim 10, further including:

    mounting a heat sink having a fifth coefficient of thermal expansion to an outer surface of

a top wall of said lid, and

matching said fifth coefficient of expansion to said second coefficient of expansion.

13. (Original) The method of claim 10, wherein said lower wall of said lid has protruding regions for maintaining equivalent contact with said thermal transfer medium on thin components of said components as is maintained by thin regions on thick components of said components.

14. (Original) The method of claim 10, further including providing supports within said vapor chamber between an upper wall of said vapor chamber and said lower wall, some or all of said supports aligned over some or all of said components.

15. (Original) The method of claim 10, wherein said package is selected from the group consisting of ball grid array modules, pin grid array modules, land grid array modules and HyperBGA<sup>TM</sup> modules.

16. (Original) The method of claim 1, wherein said lid is formed from material selected from the group consisting of aluminum, copper, Invar, gold, silver, nickel, aluminum-silicon carbide, plastics, ceramics and composites.

17. (Original) The method of claim 10, wherein said substrate includes material selected from the group consisting of ceramics, fiberglass, polytetraflouoroethylene, and polymers.

18-20. (Canceled)